# Power MOSFET –20V, 137mΩ, –2.5A, Single P-Channel

This Power MOSFET is produced using ON Semiconductor's trench technology, which is specifically designed to minimize gate charge and low on resistance. This devices is suitable for applications with low gate charge driving or low on resistance requirements.

#### **Features**

- Low On-Resistance
- 1.8V drive
- ESD Diode-Protected Gate
- Pb-Free, Halogen Free and RoHS compliance

#### **Typical Applications**

- Load Switch
- Motor Driver

#### **SPECIFICATIONS**

#### **ABSOLUTE MAXIMUM RATING** at Ta = 25°C (Note 1)

Parameter	Symbol	Value	Unit
Drain to Source Voltage	VDSS	-20	٧
Gate to Source Voltage	VGSS	±10	V
Drain Current (DC)	ID	-2.5	Α
Drain Current (Pulse) PW ≤ 10μs, duty cycle ≤ 1%	IDP	-10	Α
Power Dissipation When mounted on ceramic substrate (900mm² × 0.8mm)	PD	1	W
Junction Temperature	Tj	150	°C
Storage Temperature	Tstg	-55 to +150	°C

Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Value	Unit			
Junction to Ambient When mounted on ceramic substrate (900mm²×0.8mm)	$R_{\theta JA}$	125	°C/W			

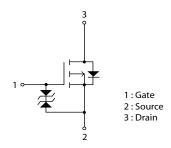


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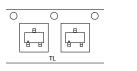
VDSS	R <sub>DS</sub> (on) Max	ID Max
	137mΩ@ –4.5V	
-20V	203mΩ@ –2.5V	-2.5A
	323mΩ@ –1.8V	

## ELECTRICAL CONNECTION P-Channel



#### PACKING TYPE: TL

#### **MARKING**





#### **ORDERING INFORMATION**

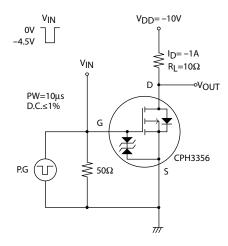
See detailed ordering and shipping information on page 5 of this data sheet.

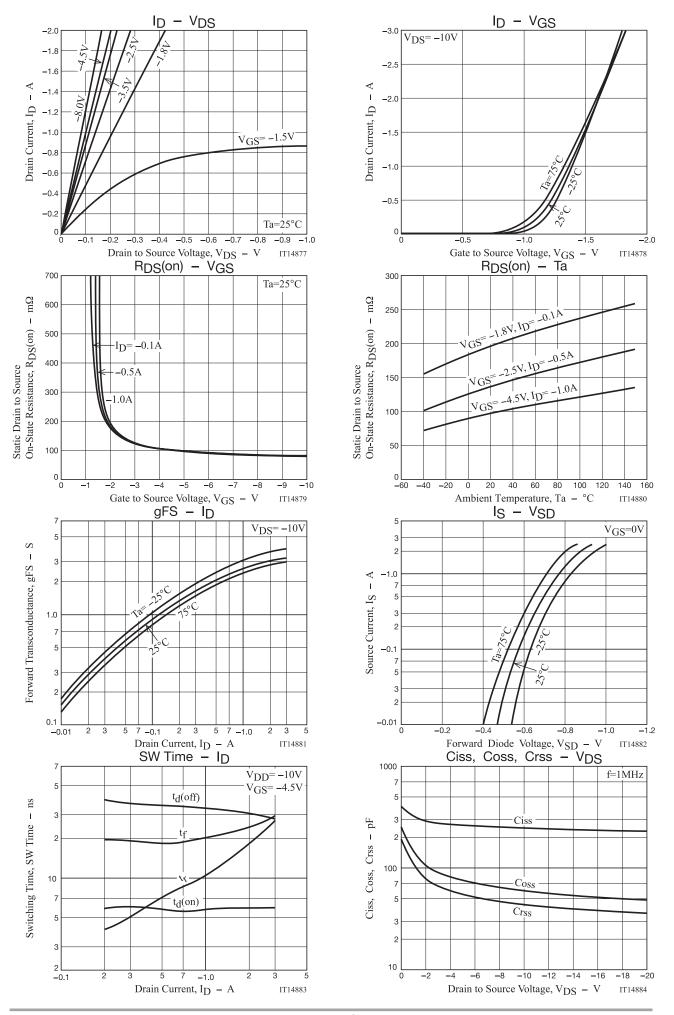
#### **ELECTRICAL CHARACTERISTICS** at Ta = 25°C (Note 2)

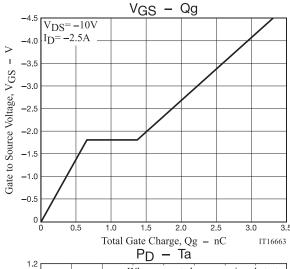
Parameter	Cymbol	Conditions	Value			Unit
Parameter	arameter Symbol Conditions		min	typ	max	Offic
Drain to Source Breakdown Voltage	V(BR)DSS	I <sub>D</sub> =-1mA, V <sub>G</sub> S=0V	-20			V
Zero-Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V			-1	μΑ
Gate to Source Leakage Current	IGSS	V <sub>GS</sub> =±8V, V <sub>DS</sub> =0V			±10	μΑ
Gate Threshold Voltage	V <sub>GS</sub> (th)	V <sub>DS</sub> =-10V, I <sub>D</sub> =-1mA	-0.4		-1.4	V
Forward Transconductance	gFS	V <sub>DS</sub> =-10V, I <sub>D</sub> =-1A		2.7		S
	R <sub>DS</sub> (on)1	I <sub>D</sub> =-1A, V <sub>G</sub> S=-4.5V		105	137	$m\Omega$
Static Drain to Source On-State Resistance	R <sub>DS</sub> (on)2	I <sub>D</sub> =-0.5A, V <sub>G</sub> S=-2.5V		145	203	mΩ
Resistance	R <sub>DS</sub> (on)3	I <sub>D</sub> =-0.1A, V <sub>G</sub> S=-1.8V		215	323	mΩ
Input Capacitance	Ciss			250		pF
Output Capacitance	Coss	V <sub>DS</sub> =–10V, f=1MHz		60		pF
Reverse Transfer Capacitance	Crss			45		pF
Turn-ON Delay Time	t <sub>d</sub> (on)			5.7		ns
Rise Time	tr			11		ns
Turn-OFF Delay Time	t <sub>d</sub> (off)	See specified Test Circuit		34		ns
Fall Time	tf			20		ns
Total Gate Charge	Qg			3.3		nC
Gate to Source Charge	Qgs	V <sub>DS</sub> =-10V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2.5A		0.65		nC
Gate to Drain "Miller" Charge	Qgd			0.72		nC
Forward Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> =-2.5A, V <sub>G</sub> S=0V		-0.87	-1.5	V

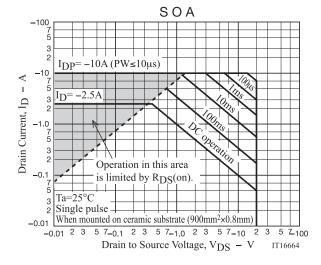
Note 2 : Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

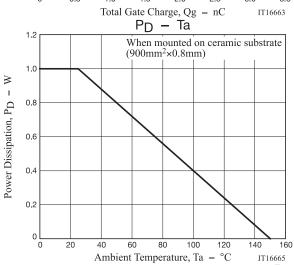
#### **Switching Time Test Circuit**

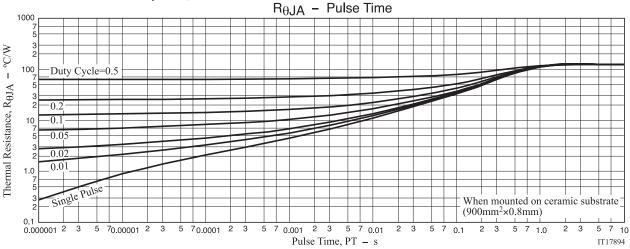






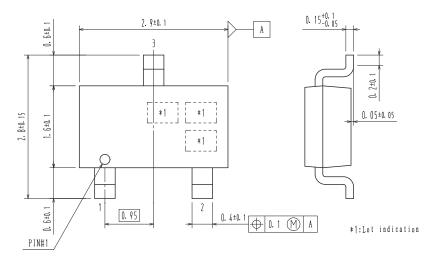






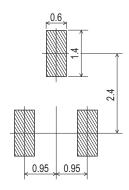
#### PACKAGE DIMENSIONS

Unit: mm CPH3 CASE 318BA ISSUE O



0.0 440.05

Recommended
Soldering Footprint



#### **ORDERING INFORMATION**

Device	Marking	Package	Shipping (Qty / Packing)	
CPH3356-TL-H	WN	CPH3 SC-59, SOT-23, TO-236	3,000 / Tape & Reel	
CPH3356-TL-W	VVIV	(Pb-Free / Halogen Free)	3,000 / Tape & Reel	

2 : Source 3 : Drain

Note on usage: Since the CPH3356 is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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<sup>†</sup> For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. http://www.onsemi.com/pub\_link/Collateral/BRD8011-D.PDF